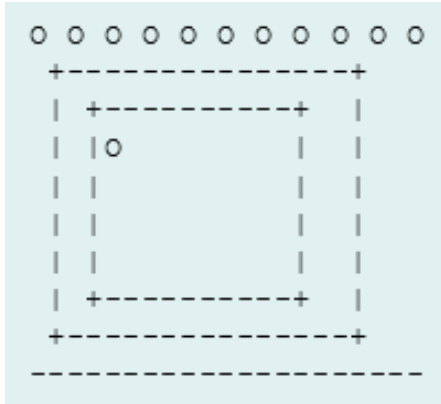
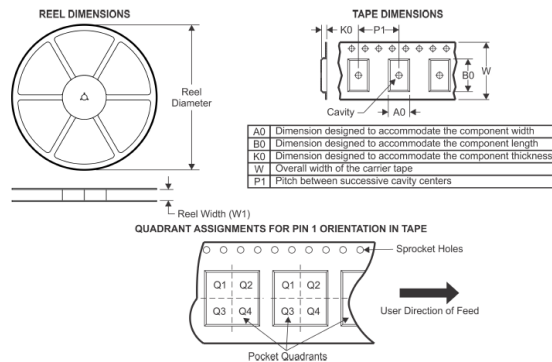


物料编码 Part number	供应 商名 称 Suppli er Name	物料信息 Info of material				最小包装信息 Info of inner packing					
		包装 方式 Packin g type	料带宽度 Width of tape (MM)	开孔 方式 Feedin g hole type	物料步 距 Feedin g step (MM)	内 装 数 量 Qty	毛重 Gross weight (KG)	包装 件 长 Leng th (MM)	包 装 件 宽 Wid th (M M)	包 装 件 高 Hig ht (M M)	包装 材质 Mate rial
BQ27426 YZFR	TI	tape reel	8		4	30 00		182	182	20	PIZZA BOX

TAPE AND REEL INFORMATION



Marking picture	vendor Name (供应商名称)	Part No. (器件型号)	Marking Rule (丝印规则)
YMLLLLS BQ27426	TI	BQ27426YZFR	丝印 BQ27426 代表型号，通过识别本体丝印 BQ27426 可判定物料正确 the marking " BQ27426" represents the device name, by identifying units marking BQ27426 correctly to determine device

TI Part	Component	Homogeneous Material Name.	Substance Name	*CAS No.	Substance Mass. (mg)	Content Rate(%)
BQ27426YZFR	Back Side Coating	Other Inorganic Materials	Silica	7631-86-9	0.097736	55.066879
		Other Plastics and Rubber	Carbon Black	1333-86-4	0.003003	1.691964
		Other Plastics and Rubber	Imidazole Derivative	288-32-4	0.000667	0.375804
		Thermoplastics	Epoxy	85954-11-6	0.07608	42.86535
	Solder Bump	Copper and Its Alloys	Copper	7440-50-8	0.002741	0.499958
		Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.523575	95.500013
		Precious Metals	Silver	7440-22-4	0.02193	4.00003
	Semiconductor Device	Ceramics / Glass	Doped Silicon	7440-21-3	1.747418	100

类别 Category	Basic Information		Result
基本信息 General Information	供应商名称 Supplier Name		TI
	器件型号 Device Part Number		BQ27426YZFR
晶圆信息 Wafer related Information	晶圆代工厂信息，工艺类别和工艺节点 Wafer fab information, process type and node		RFAB / DMOS6
	该晶圆工艺是否成熟 wafer process was or not qualified and released to production.		Mature
	客户已使用的同晶圆族器件（同工艺技术、同工厂） Is there any part from the same wafer process family have been used in customer? If yes, please list the part number.		YES
	晶圆工艺制程能力（SPC） Wafer Process Capability(SPC)		Meet SPC spec

	是否存在 Cpk<1.33 的制程监控参数？如有，请列出该监控参数及其改进计划。 Is there any wafer process CPK<1.33? If yes, please list it and provide the improvement plan.		NO
	芯片 ID Chip ID:Do you have chip ID or die ID for this device?		NO
封装信息 Assembly related Information	封装代工厂，封装类型 Assembly Factory, Package type		Clark WCSP
	封装尺寸（长*宽*高） Package Size (Length*Width*Height)		1.8x1.8x0.65mm
	焊球/引脚间距 Ball/Lead pitch		0.5MM
	客户已使用的同封装族器件（同封装技术、同封装厂） Is there any part from the same package family have been used in customer? If yes, please list the part number.		YES
	键合工艺 Wire Bonding (Only for Wire Bonding Package)	键合线成分 Wire composition	NA
		键合线直径 Wire diameter	NA
	封装工艺制程能力（SPC） Assembly Process Capability(SPC)		Meet SPC spec
	是否存在 Cpk<1.33 的制程监控参数？如有，请列出该监控参数及其改进计划。 Is there any assembly process CPK<1.33? If yes, please list it and provide the improvement plan.		NO
	工作温度范围 Range of Operation Temperature (Ta, Tj or Tc)		-40~85C
	存储温度范围 Storage Temperature range		-65 ~ 150C
	存储期限 Storage limit		1years at customer side
	最大结温 Max.Junctioin Temperature		NA
	长期失效率 IFR, Intrinsic Failure Rate, FIT		0.2FIT@60%CL
	潮湿敏感等级 MSL, Moisture Sensitive Level		MSL 1

可靠性认证 Reliability Qualification	封装热阻 Theta ja, jc and jb	Θja	64.1 °C/W
		Θjc	59.8°C/W
		Θjb	52.7°C/W
	ESD (HBM、CDM, for all pin)	HBM	1500
		CDM	250
	抗闩锁能力 Latch-Up (At max. Ambient Temperature)		Meet qual test requirement
可靠性认证 Reliability Qualification	新工艺或新设计器件的可靠性或寿命极限测试数据 If the chip is new process or new design, And some Lifetime limit test (Test to fail or beyond JEDEC standard) had been down. Please specify the test condition and result detailly.		NO
	晶圆可靠性认证报告 Wafer reliability Qualification Report, including: TDDb, HCI, NBTI, PBTI, EM, SM .etc		YES
	封装可靠性认证报告 Package Qualification Report, including: PC, THB, HAST, UHAST, HTSL, TC, BLTC, DT, Bend, PDT, PVT .etc		See TI.com qual report
	器件可靠性认证报告 Device Qualification Report, including: ELFR, HTOL, LTOL, ASER, SSER, ESD-HBM, ESD-CDM, LU .etc		See TI.com qual report
	器件量产后应该进行可靠性试验监控，请提供最新的可靠性监控报告 The device should be done reliability monitoring. Please provide the latest Reliability Monitoring Report, including: PC, THB, HAST, UHAST, TC, HTSL, HTOL .etc		ORT test is based on package
	性能报告 Characterization report, follow JESD86		Can't provide

器件信息 Component information	调查结果 Investigation Result
焊球材料成分及含量 Ball Compositions and ratio	SAC405
	其它 Other(please specify):
焊球植球前的球粒直径(μm) Ball Diameter(μm) before ball attachment	0.3MM
是否背胶处理 Back side laminate	Yes
WLCSP 器件是否有 RDL 层(再分布引线层) is there RDL layer in WLCSP?	Yes
封装遵循的标准 Package standard	JEDEC
	其它 other(please specify):
元器件重量 Weight of component (g)	2.5mg
元件重量/贴片吸取面积是否≤0.06g/mm2 Weight/ available P&P area≤0.06g/mm2	是 Yes
	如果不满足，请给出具体值: If not, give the actual data:
器件上表面 MARK 信息是否有方向性标志点（例如“1”引脚标志）？ Is there polarity point on the top side of component?	是 Yes
器件表面方向性标志点是否唯一?(如果不唯一请附图说明标志点与引脚对应关系。) Is the polarity point sole? (if not, pleases indicate the correspondence between the polarity point and balls)	是 Yes
器件资料是否明确标注引脚位置号？ Is there any specific location number of terminals in component specification?	是 Yes

方向性器件在 AOI 上实际确认，需要设备能识别器件极性 component orientation can be identified by AOI?		是 Yes
下面所列物质的重量比是否满足 RoHS 要求？（请参考此调查表的“sheet7 RoHS Compliant”） 铅、镉、汞、六价铬、多溴联苯、多溴二苯醚 Are matters RoHS compliant listed below? (please refer to "sheet7 RoHS Compliant" in this file) Lead, Cd, Hg, Cr VI, PBB, PBDE Lead-free		是 Yes
是否无卤 Halogen-free		是 Yes
存储 Storage	相对湿度（%） Relative humidity (%)	$\geq 20\% \& \leq 70\%$ 其它 other (please specify):
	温度（℃） Temperature (℃)	$\geq -10^{\circ}\text{C} \& \leq 35^{\circ}\text{C}$ 其它 other (please specify):
	可存储期限（月） Maximum storage time (month)	12 其它 other (please specify):
表贴元器件包装类型 Packaging type		卷带包装 tape and reel 其它 other (please specify):
器件 pin1 脚标识在包装中的位置（见右图 2） Position of component pin 1 in packing (see right figure 2)		Figure 1
料带或 Tray 盘高度（H），见右图 3 Packaging height(H), see right figure 3		0.69mm
包装宽度（W），见右图 3 Packaging width(W), see right figure 3		8mm
卷带器件料带步距:P1 component pitch:P1		4mm

防静电包装 ESD packaging	是 Yes
能否满足：料带包装中侧翻率 $\leq 0.05\%$ Rollover rate $\leq 0.05\%$ in packing	是 Yes
能否承受：托盘包装 125℃/24 小时的烘烤条件 tray packing Baking conditions: 125℃@24h	是 Yes
能否承受：卷带包装 40℃/192 小时的烘烤条件 reel tape packing Baking conditions: 40℃@192h	是 Yes
卷带包装是否符合 EIA-481 标准? can reel tape packing meet EIA-481 standard?	EIA
	其它 other(please specify):
潮湿敏感等级 MSL	1
潮敏等级在 2 级及 2 级以上，潮敏防护必须包含：潮敏指示卡、干燥剂、潮敏等级标识等 Moisture sensitive level at level 2 and level 2 above, moisture sensitive protection must include: moisture sensitive indicator card, desiccant, moisture sensitive grade logo	是 Yes
受潮后的烘烤要求是否满足 J-STD-033b.1 Baking requirement if moisture	是 Yes
是否满足：能承受的回流焊接次数 ≥ 3 次 Maximum soldering times ≥ 3	是 Yes
	如无法满足，请填写实际规格: If not, please specify:
针对表贴器件，其耐温性是否满足 J-STD-020D 要求？（重点关注耐温性和回流曲线分级两部分，即表 4-1，4-2 和 5-2，请参考此调查表“sheet6 J-STD-020D”） Can heat resistance of SMT components meet JSTD020D. (should focus on the classification of temperature and reflow profiles, that is table 4-1, 4-2 and 5-2, please refer to sheet6 J-STD-020D in this file)	是 Yes
是否满足：表贴器件中心能承受的贴片压力 $\geq 2N$ Maximum pick-and-place pressure (N)	是 Yes

器件的焊接加工和设计要求是否已经全部写入器件规格书？ Whether the welding process and design requirements of component have all written to the component specifications	是 Yes
器件规格书中提供的焊盘及钢网设计（包括钢网厚度）是否为强制要求？ Whether Pad & stencil design as Mandatory requirements in component spec?	如有设计要求，请在此说明
器件对回流焊升温斜率和降温斜率是否有特殊要求？ 客户采用 J-STD-002D 标准 Whether the device has special requirements for the reflow temperature ramp-up rata and ramp-down rata? Customer follow J-STD-002 standard	推荐 recommended
器件规格书中是否有其他强制要求？ Are there other mandatory requirements in component spec?	无 No
可焊性测试除使用助焊剂和锡膏按照下列要求执行外，其余条件及方法根据 J-STD-002D 标准执行，并提供测试报告。 待测试样品需经过蒸汽老化 8 小时预处理，再做可焊性测试。 1.焊料温度 可焊性检测时焊料的温度维持在 245℃±5℃。 2.锡膏 无铅测试锡膏成分应该为 Sn96.5/Ag3.0/Cu0.5 (SAC305)。锡膏采用 ROL0 型，4 号粉或者 5 号粉。 3.焊剂 可焊性测试采用非活性天然松香基液体焊剂，型号为 ROL0。 4.针对 BGA 封装，请采用陶瓷载板法进行焊球可焊性测试，即在陶瓷载板上按照焊球矩阵印锡并回流焊接 BGA，之后将 BGA 整个起拔，陶瓷载板上无锡膏残留即可焊性满足要求。	如有其他特殊要求，请在此说明
Solderability shall be tested per J-STD-002D and the report must be offered, some special demands are required as below. The sample to be tested shall be pretreated with steam for 8 hours before solderability testing. 1. soldering temperature 245℃±5℃ for lead-free 2. solder paste the composition of solder paste must be Sn96.5/Ag3.0/Cu0.5 (SAC305) for lead-free. The type of solder paste must be ROL0, type4 or 5. 3. flux the flux must be a non-active rosin flux, type ROL0. 4. BGA package use ceramic substrate to test. Print the solder paste onto	无 No 如有其他强制要求，请在此说明 是 Yes 添加报告 please add test report here

the test substrate follow the solder ball pattern, and reflow the samples. After reflow, remove components from substrate. The solderability can meet requirement if there is no solder paste remain on substrate.	
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